MicroCoat Technologies, LLC

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MicroCoat Technologies, a coatings, and adhesives development company was formed in 1996 by Sam Forman a veteran of over 60 years in polymer and thick film materials. He is a Founding and Charter Member, Fellow of the Society and Life Member of IMAPS, and also the recipient of the IMAPS Lifetime Achievement and Daniel C. Hughes awards.

The Company specializes in advanced conductive, non-conductive, and UV cure adhesives and coatings formulations for the electronics, microelectronics, and semiconductor industries that supply products to the Aerospace, Defense, Medical, Opto-electronics, Telecommunications, Down-hole, and also the commercial sector of assemblies. With over 150 combined years of polymer expertise, MicroCoat has developed unquestionably the finest fine-line no-bleed conductive adhesives and "sintered' silver adhesives with a TC of >150W/mK. Our non-conductive sealing adhesives have passed *MSL1* testing for many companies. The Company ships several thousand syringes each month of conductive and non-conductive die attach adhesives, globtop, dam, and fill formulations for semiconductor assemblies and MCM's worldwide. MicroCoat's "B" staged conductive and non-conductive films and liquids are used extensively for both die attach and package sealing.

Epoxy Ring Bleedout Issues Solved

With substrate real estate shrinking to *"I can barely see it"* dimensions, die placement very close to active wirebond areas was a major issue as pretty much all available adhesives had epoxy ring runout of as much 300-500um. Wirebonding down from a die or to a die with lines and wire placement as close as 250um is now pretty much standard. MicroCoat Technologies has developed their MiniDot technology with <50um bleed-out for conductive and non-conductive die-attach adhesives as the adhesives of choice for very small die, micro BGA's, MCM, etc. placement/attachment.

Our library of over 3000 UV cure coatings is specifically formulated for the PCB Assembly/SMT, Medical, and Optoelectronics industries. MicroCoat UV cure or UV/Heat cure, globtops, dams, and fills are filled or unfilled. MicroCoat satisfies the most stringent of adhesives requirements.

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